

## RADIATION HARDENED POWER MOSFET THRU-HOLE (TO-39)

**IRHF7430SE**  
**JANSR2N7464T2**  
**500V, N-CHANNEL**  
**REF: MIL-PRF-19500/676**

**RAD Hard™ HEXFET® TECHNOLOGY**

### Product Summary

Part Number	Radiation Level	RDS(on)	ID	QPL Part Number
IRHF7430SE	100K Rads (Si)	1.65Ω	2.6A	JANSR2N7464T2



International Rectifier's RADHard™ HEXFET® MOSFET technology provides high performance power MOSFETs for space applications. This technology has over a decade of proven performance and reliability in satellite applications. These devices have been characterized for both Total Dose and Single Event Effects (SEE). The combination of low RDS(on) and low gate charge reduces the power losses in switching applications such as DC to DC converters and motor control. These devices retain all of the well established advantages of MOSFETs such as voltage control, fast switching, ease of paralleling and temperature stability of electrical parameters.

### Features:

- Single Event Effect (SEE) Hardened
- Ultra Low RDS(on)
- Low Total Gate Charge
- Neutron Tolerant
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Light Weight

### Absolute Maximum Ratings

### Pre-Irradiation

	Parameter		Units
ID @ VGS = 12V, TC = 25°C	Continuous Drain Current	2.6	A
ID @ VGS = 12V, TC = 100°C	Continuous Drain Current	1.6	
IDM	Pulsed Drain Current ①	10.4	
PD @ TC = 25°C	Max. Power Dissipation	25	W
	Linear Derating Factor	0.2	W/°C
VGS	Gate-to-Source Voltage	±20	V
EAS	Single Pulse Avalanche Energy ②	148	mJ
IAR	Avalanche Current ①	2.6	A
EAR	Repetitive Avalanche Energy ①	2.5	mJ
dv/dt	Peak Diode Recovery dv/dt ③	8.0	V/ns
TJ	Operating Junction	-55 to 150	°C
TSTG	Storage Temperature Range		
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10 sec.)	
	Weight	0.98 (Typical)	g

For footnotes refer to the last page

**Electrical Characteristics @ T<sub>j</sub> = 25°C (Unless Otherwise Specified)**

	Parameter	Min	Typ	Max	Units	Test Conditions
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	500	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1.0mA
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Temperature Coefficient of Breakdown Voltage	—	0.56	—	V/°C	Reference to 25°C, I <sub>D</sub> = 1.0mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-State Resistance	—	—	1.6	Ω	V <sub>GS</sub> = 12V, I <sub>D</sub> = 1.6A ④
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.5	—	4.5	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1.0mA
g <sub>fs</sub>	Forward Transconductance	0.8	—	—	S (r)	V <sub>DS</sub> > 15V, I <sub>DS</sub> = 1.6A ④
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	—	—	50	μA	V <sub>DS</sub> = 400V, V <sub>GS</sub> = 0V
		—	—	250		V <sub>DS</sub> = 400V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125°C
I <sub>GSS</sub>	Gate-to-Source Leakage Forward	—	—	100	nA	V <sub>GS</sub> = 20V
I <sub>GSS</sub>	Gate-to-Source Leakage Reverse	—	—	-100		V <sub>GS</sub> = -20V
Q <sub>g</sub>	Total Gate Charge	—	—	30	nC	V <sub>GS</sub> = 12V, I <sub>D</sub> = 2.6A V <sub>DS</sub> = 250V
Q <sub>gs</sub>	Gate-to-Source Charge	—	—	7.0		
Q <sub>gd</sub>	Gate-to-Drain ('Miller') Charge	—	—	18		
t <sub>d(on)</sub>	Turn-On Delay Time	—	—	30	ns	V <sub>DD</sub> = 250V, I <sub>D</sub> = 2.6A, V <sub>GS</sub> = 12V, R <sub>G</sub> = 7.5Ω
t <sub>r</sub>	Rise Time	—	—	60		
t <sub>d(off)</sub>	Turn-Off Delay Time	—	—	65		
t <sub>f</sub>	Fall Time	—	—	45		
LS + LD	Total Inductance	—	7.0	—	nH	Measured from drain lead (6mm/0.25in. from package) to source lead (6mm/0.25in. from package)
C <sub>iss</sub>	Input Capacitance	—	620	—	pF	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V f = 1.0MHz
C <sub>oss</sub>	Output Capacitance	—	148	—		
C <sub>rss</sub>	Reverse Transfer Capacitance	—	52	—		

**Source-Drain Diode Ratings and Characteristics**

	Parameter	Min	Typ	Max	Units	Test Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)	—	—	2.6	A	
I <sub>SM</sub>	Pulse Source Current (Body Diode) ①	—	—	10.4		
V <sub>SD</sub>	Diode Forward Voltage	—	—	1.4	V	T <sub>j</sub> = 25°C, I <sub>S</sub> = 2.6A, V <sub>GS</sub> = 0V ④
t <sub>rr</sub>	Reverse Recovery Time	—	—	600	nS	T <sub>j</sub> = 25°C, I <sub>F</sub> = 2.6A, di/dt ≤ 100A/μs V <sub>DD</sub> ≤ 50V ④
Q <sub>RR</sub>	Reverse Recovery Charge	—	—	2.2	μC	
t <sub>on</sub>	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by LS + LD.				

**Thermal Resistance**

	Parameter	Min	Typ	Max	Units	Test Conditions
R <sub>thJC</sub>	Junction-to-Case	—	—	5.0	°C/W	
R <sub>thJA</sub>	Junction-to-Ambient	—	—	175		Typical socket mount

**Note:** Corresponding Spice and Saber models are available on the G&S Website.

For footnotes refer to the last page

International Rectifier Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at International Rectifier is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

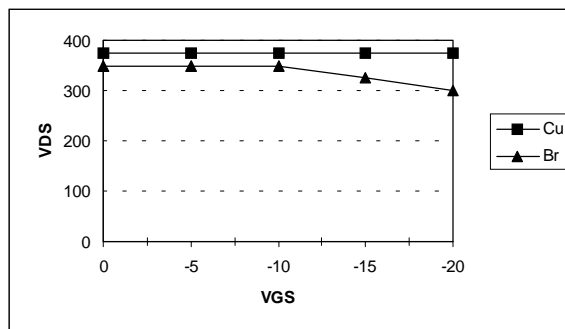
**Table 1. Electrical Characteristics @  $T_j = 25^\circ\text{C}$ , Post Total Dose Irradiation ⑤⑥**

	Parameter	100K Rads (Si)		Units	Test Conditions ⑧
		Min	Max		
$BV_{DSS}$	Drain-to-Source Breakdown Voltage	500	—	V	$V_{GS} = 0V, I_D = 1.0mA$
$V_{GS(th)}$	Gate Threshold Voltage	2.0	4.5		$V_{GS} = V_{DS}, I_D = 1.0mA$
$I_{GSS}$	Gate-to-Source Leakage Forward	—	100	nA	$V_{GS} = 20V$
$I_{GSS}$	Gate-to-Source Leakage Reverse	—	-100		$V_{GS} = -20V$
$I_{DSS}$	Zero Gate Voltage Drain Current	—	50	$\mu A$	$V_{DS} = 400V, V_{GS} = 0V$
$R_{DS(on)}$	Static Drain-to-Source ④ On-State Resistance (TO-3)	—	1.6	$\Omega$	$V_{GS} = 12V, I_D = 1.6A$
$R_{DS(on)}$	Static Drain-to-Source ④ On-State Resistance (SMD-0.5)	—	1.6	$\Omega$	$V_{GS} = 12V, I_D = 1.6A$
$V_{SD}$	Diode Forward Voltage ④	—	1.4	V	$V_{GS} = 0V, I_D = 2.6A$

International Rectifier radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

**Table 2. Single Event Effect Safe Operating Area**

Ion	LET ( $\text{MeV}/(\text{mg}/\text{cm}^2)$ )	Energy (MeV)	Range ( $\mu\text{m}$ )	$V_{DS}$ (V)				
				@ $V_{GS}=0V$	@ $V_{GS}=-5V$	@ $V_{GS}=-10V$	@ $V_{GS}=-15V$	@ $V_{GS}=-20V$
Cu	28	285	43	375	375	375	375	375
Br	38	305	39	350	350	350	325	300



**Fig a. Single Event Effect, Safe Operating Area**

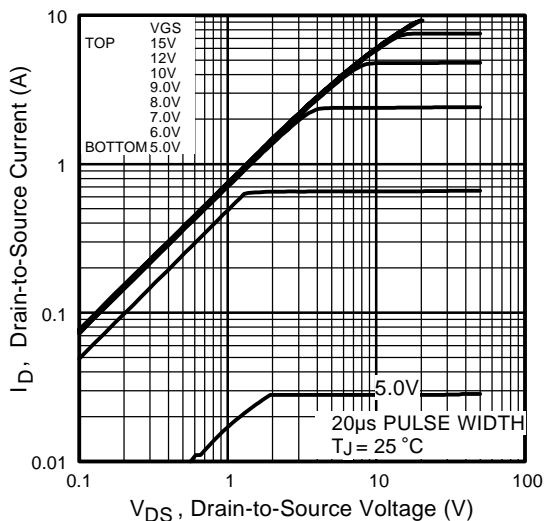


Fig 1. Typical Output Characteristics

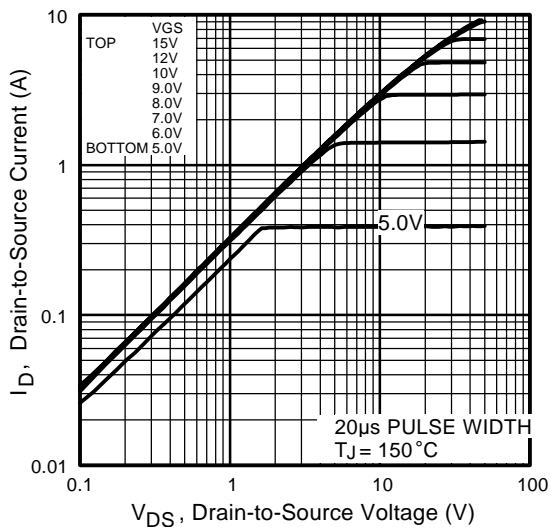


Fig 2. Typical Output Characteristics

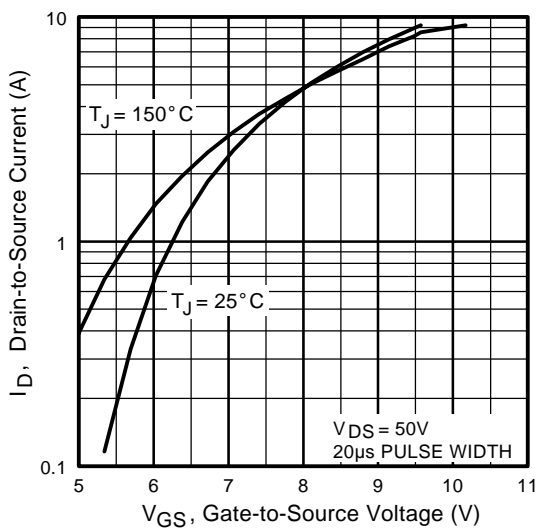


Fig 3. Typical Transfer Characteristics

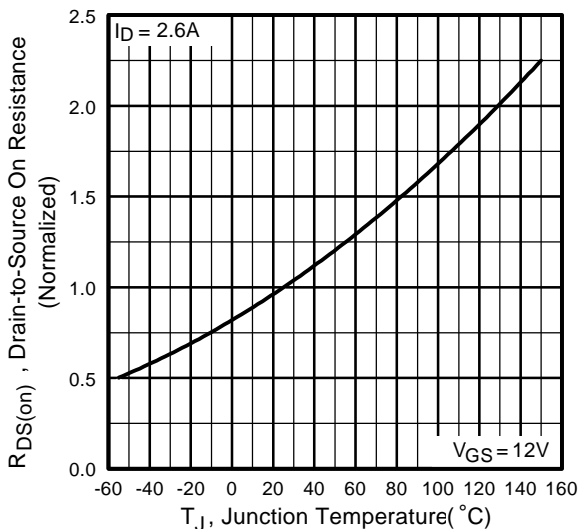


Fig 4. Normalized On-Resistance Vs. Temperature

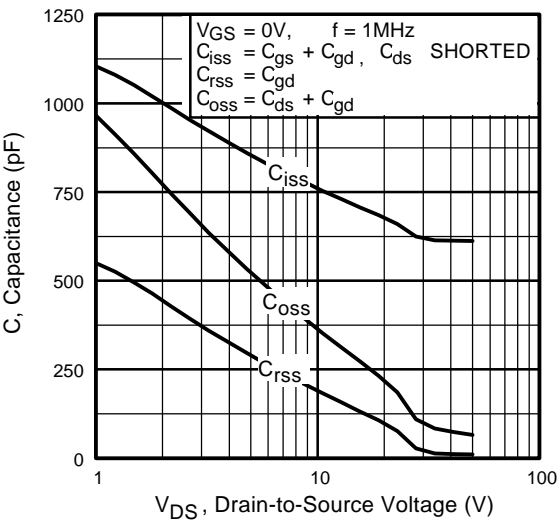


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

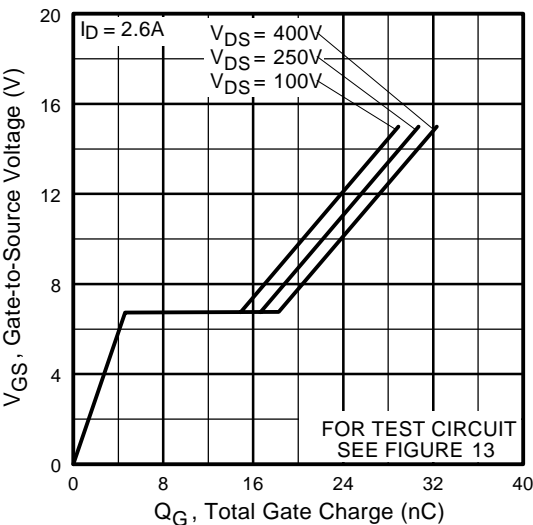


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

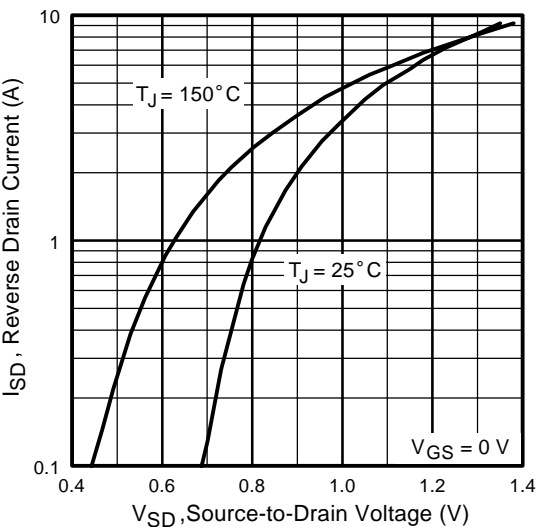


Fig 7. Typical Source-Drain Diode Forward Voltage

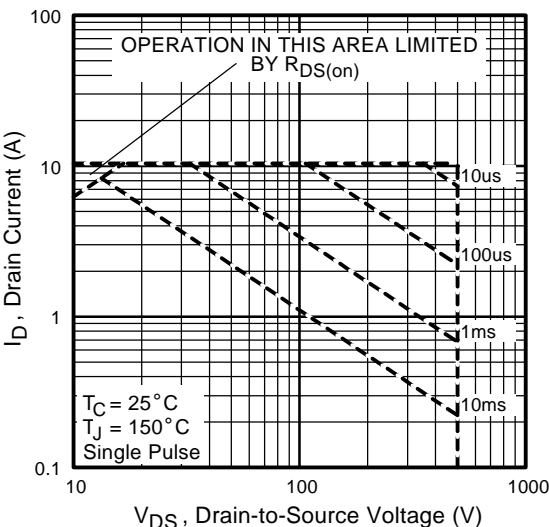
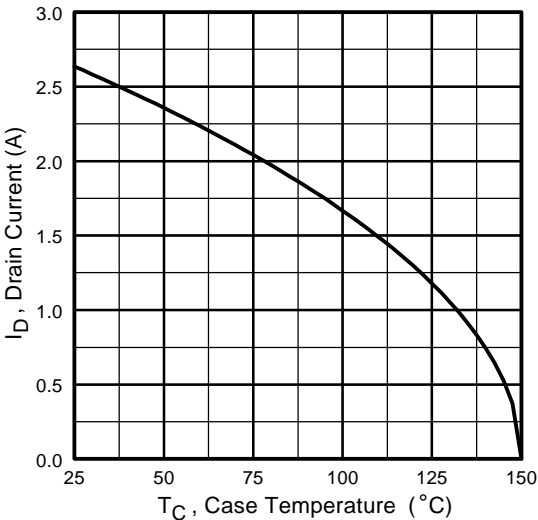
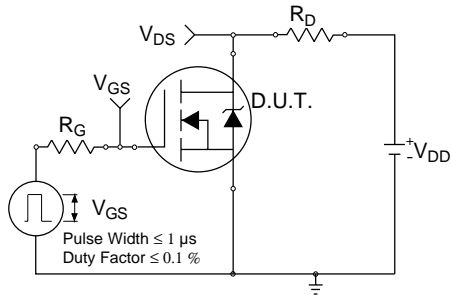


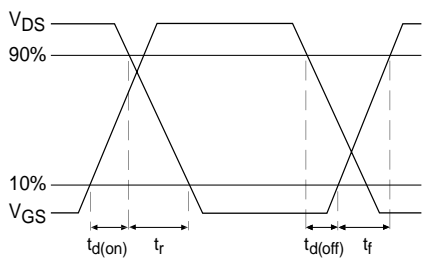
Fig 8. Maximum Safe Operating Area



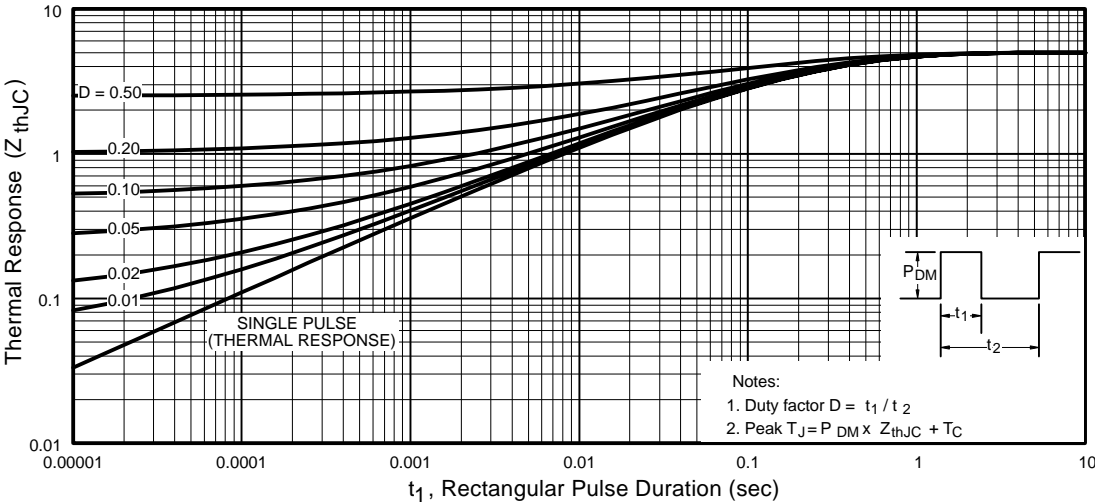
**Fig 9.** Maximum Drain Current Vs. Case Temperature



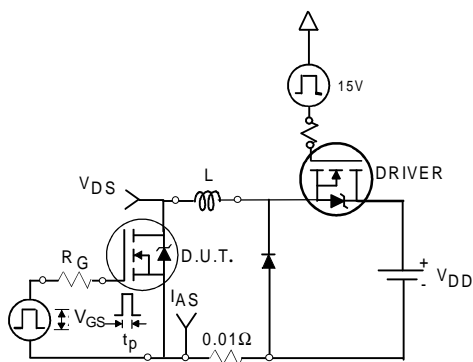
**Fig 10a.** Switching Time Test Circuit



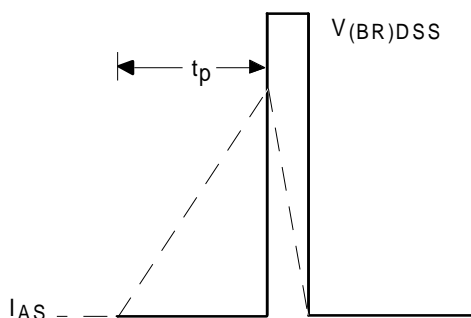
**Fig 10b.** Switching Time Waveforms



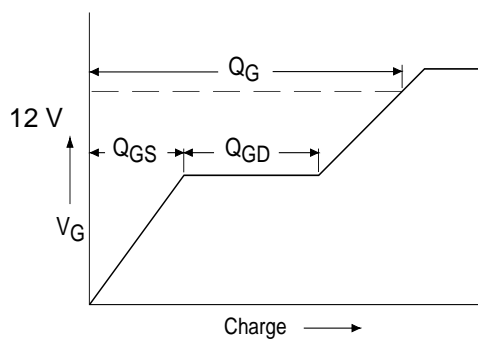
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case



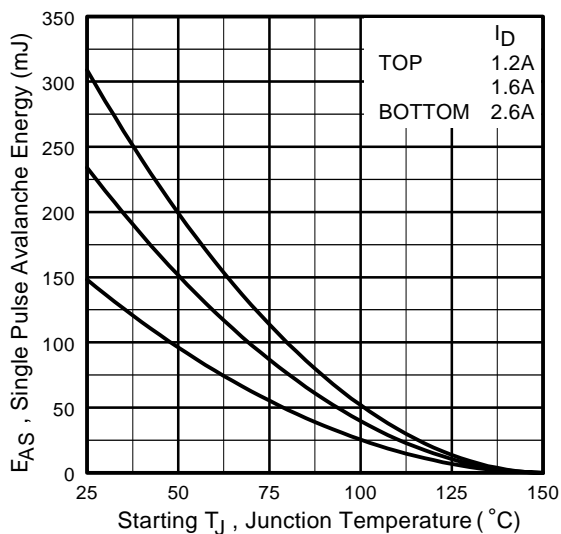
**Fig 12a. Unclamped Inductive Test Circuit**



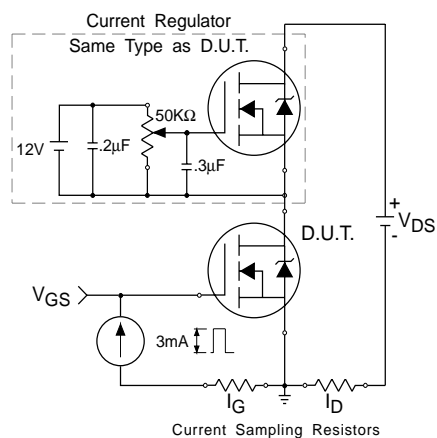
**Fig 12b. Unclamped Inductive Waveforms**



**Fig 13a.** Basic Gate Charge Waveform



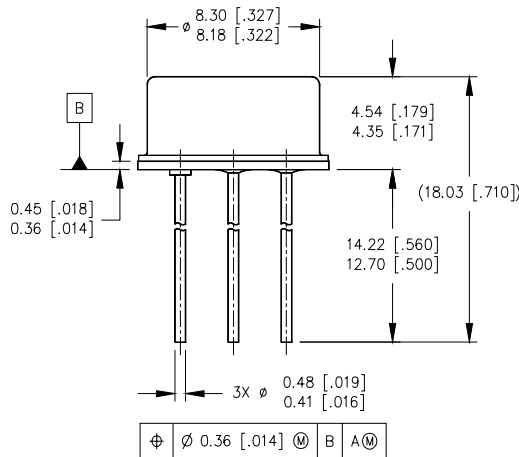
**Fig 12c. Maximum Avalanche Energy Vs. Drain Current**



### Fig 13b. Gate Charge Test Circuit

**Footnotes:**

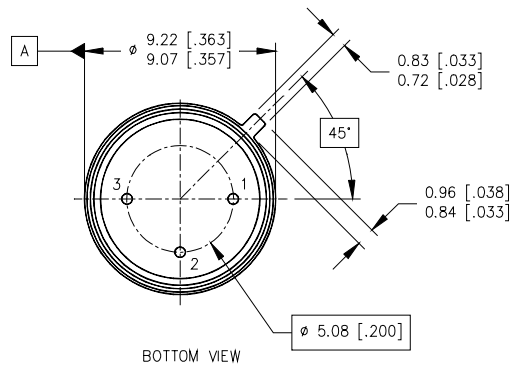
- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ②  $V_{DD} = 50V$ , starting  $T_J = 25^\circ C$ ,  $L = 7.0\text{ mH}$   
Peak  $I_L = 2.6A$ ,  $V_{GS} = 12V$
- ③  $I_{SD} \leq 2.6A$ ,  $di/dt \leq 400A/\mu s$ ,  
 $V_{DD} \leq 500V$ ,  $T_J \leq 150^\circ C$
- ④ Pulse width  $\leq 300\text{ }\mu s$ ; Duty Cycle  $\leq 2\%$
- ⑤ **Total Dose Irradiation with  $V_{GS}$  Bias.**  
12 volt  $V_{GS}$  applied and  $V_{DS} = 0$  during irradiation per MIL-STD-750, method 1019, condition A.
- ⑥ **Total Dose Irradiation with  $V_{DS}$  Bias.**  
400 volt  $V_{DS}$  applied and  $V_{GS} = 0$  during irradiation per MIL-STD-750, method 1019, condition A.

**Case Outline and Dimensions — TO-205AF (Modified TO-39)**

SIDE VIEW

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME 14.5M-1994.
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. CONTROLLING DIMENSION: INCH.
4. CONFORMS TO JEDEC OUTLINE TO-205AF (TO-39).

**LEGEND**

- 1- SOURCE
- 2- GATE
- 3- DRAIN

International  
**IR** Rectifier

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